



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC011N03LST	Issued	08. April 2021
MA#	MA001708824		
Package	PG-TDSON-8-17	Weight*	119.21 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.077	0.90	0.90	9031	9031
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		317	
	non noble metal	copper	7440-50-8	37.762	31.68	31.72	316755	317167
wire	noble metal	gold	7440-57-5	0.041	0.03	0.03	343	343
encapsulation	organic material	carbon black	1333-86-4	0.132	0.11		1106	
	plastics	epoxy resin	-	5.143	4.31		43137	
	inorganic material	silicondioxide	60676-86-0	38.679	32.46	36.88	324449	368692
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12177	12177
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1388	1388
solder	non noble metal	tin	7440-31-5	0.030	0.02		248	
	noble metal	silver	7440-22-4	0.037	0.03		310	
	non noble metal	lead	7439-92-1	1.410	1.18	1.23	11827	12385
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	zinc	7440-66-6	0.013	0.01		113	
	non noble metal	iron	7439-89-6	0.269	0.23		2254	
	non noble metal	copper	7440-50-8	10.909	9.15	9.39	91508	93903
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	zinc	7440-66-6	0.026	0.02		222	
	non noble metal	iron	7439-89-6	0.529	0.44		4438	
	non noble metal	copper	7440-50-8	21.482	18.02	18.49	180199	184914
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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